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Presented by: Eszter Lukács IEEE Client Services Manager <u>e.lukacs@ieee.org</u>





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Read: 2022-2024

- IEEE All-Society Periodicals Package (ASPP) (backfile from 2005)
- IEEE Proceedings Orders Plans (POP) (backfile from 2005)

Publish: 2022-2024: Publish 180 APCs in IEEE Gold or Hybrid journals

- Eligible Author: corresponding author who is affiliated with a HEAL Link Institution, (based on RINGGOLD or email domain)
- Eligible costs: Only open access charges are covered by the agreement. Color and over-length charges (not mandatory) are not included and must be paid by the authors.
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^{*} Source: Journal Citation Reports (Clarivate Analytics, 2022)

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Journal Citation Reports[®] by Impact Factor

IEEE publishes:

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- 3 of the top 5 journals in Automation & Control Systems
- 3 of the top 5 journals in Computer Science: Artificial Intelligence
- 3 of the top 5 journals in Computer Science: Hardware & Architecture
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Source: Journal Citation Reports (Clarivate Analytics, 2022)

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- In addition to the existing direct open access agreements with hundreds of institutions, all of IEEE's hybrid journals now qualify as 'Transformative Journals' under Plan S.
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- Conferences are for preliminary findings of ongoing research
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Writing the Article



Components of a Typical Article

Title	Specific, concise, descriptive
Abstract	Describe research in 250 words or less
Introduction	Novelty, goal, and motivation
Approach and Results	What you did, how you did it, and what results you obtained
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Peer review process and what editors and reviewers are looking for



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Telecommunications Systems Institute (TSI) Technical University of Crete Chania, Greece

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radiofrequency identification, backscatter, direction-of-arrival estimation, receiving antennas, software radio, antenna arrays, probability, telecommunication power management, SLAM (robots), array signal processing, energy harvesting, error statistics, mobile robots, phase measurement, protocols, radio **Show More**

Biography

Aggelos Bletsas (Senior Member, IEEE) received the Diploma degree (Hons.) in electrical and computer engineering from the Aristotle University of Thessaloniki, Greece, in 1998, and the S.M. and Ph.D. degrees from MIT, Cambridge, MA, USA, in 2001 and 2005, respectively. Currently, he is a Professor with the School of Electrical and Computer Engineering, Technical University of Crete, Greece. His research interests include span the broad area of scalable wireless communications and sensor networking. He was a co-recipient of the IEEE





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Shreshth Tuli; Shivananda R. Poojara; Satish N. Srirama; Giuliano Casale; Nicholas R. Jennings IEEE Transactions on Parallel and Distributed Systems

Year: 2022 | Volume: 33, Issue: 1 | Journal Article | Publisher: IEEE

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Abstract

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A2GAN: A Deep Reinforcement-Based Learning Algorithm for Risk-Aware in Finance Tuyen Pham Le; Cheolkyun Rho; Yelin Min; Sungreong Lee; Daewoo Choi IEEE Access Year: 2021 | Volume: 9 | Journal Article | Publisher: IEEE



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